

## OS-2.9 Panel Feedthrough Plug Receptacle Field Replaceable 1060034-1

408–4629 08 FEB 00 Rev O EC 0990-0122-00

Instruction Sheet

CONNECTOR TYPE

OS-2.9 PANEL FEEDTHROUGH PLUG RECEPTACLE, FIELD REPLACEABLE

CABLE **TYPE** 

N/A

TOOLS REQ'D SOLDER FIXTURE: 2598-5285-54,
TORQUE KIT: 2598-5985-5287-54
STEP DRLL: 2598-5286-54,
Z598-5297-54
TAPPING DRLL: 2598-5287-54
SOLDER: NOALLOY 6#2
FILUX: KESTER 6#97
CLEANING RUID: ISOPROPYL ALCOHOL

HOUSING SUB-ASSY CONNECTOR

BUSHING SUB-ASSY

### ASSEMBLY OPERATIONS

MOUNTING HOLE PREPARATION

1 USING THE STEP DRILL, P/N 2598-5286-54
(2598-5292-54 FOR STRESS RELIEF
CONTACT APPLICATIONS), REAM MOUNTING
HOLE TO DEPTH SHOWN.

2 TAP A .250-36 UNS-2B THREAD TO DEPTH
SHOWN.

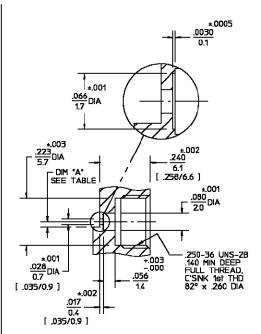
3 CLEAN WITH SOLVENT.

1.2

# RECOMMENDED DIMENSIONS FOR BOARD THICKNESS VARIATIONS

| BOARD     | DIM .V. |
|-----------|---------|
| THICKNESS | ±.001   |
| .010      | . 019   |
| .015      | . 024   |
| . 020     | . 029   |
| . 025     | . 034   |

NOTES:
1. DIA'S CONCENTRIC WITHIN .002 TIR
2. DIMENSIONS ARE IN IN/(MM).
3. DIMENSIONS IN BRACKETS APPLY IF
STRESS RELIEF CONTACTS ARE USED.



#### OPTION 1

- OPTION 1

  2.0 INSTALLATION OF HERMETIC SEAL
  2.1 CLEAN HERMETIC SEAL IN ISOPROPYL
  ALCOHOL.
  2.2 APPLY FLUX TO THE OUTER CONDUCTOR OF
  THE HERMETIC SEAL. CARE SHOULD BE
  TAKEN TO AVOID GETTING FLUX ON THE
  CENTER PIN.
  2.3 INSERT SEAL INTO THE MOUNTING HOLE
  WITH THE SHORT PIN END TOWARDS THE
  .028±.001 DIA HOLE. SUCH THAT THE
  PIN EXTENDS THROUGH THE PANEL AS
  SHOWN.
  2.4 PLACE A RING OF SOLDER ON THE LIP OF
  THE SOLDER FIXTURE PLUNGER AS SHOWN.
  2.5 SCREW THE SOLDER FIXTURE INTO THE
  MOUNTING HOLE AS SHOWN.
  2.6 HEAT THE PANEL TO ALLOW SOLDER TO
  FLOW. NOTE: INDALLOY #2 SOLDER FLOWS
  AT 14.9°C.
  2.7 REMOVE FROM HEAT SOURCE AND ALLOW TO

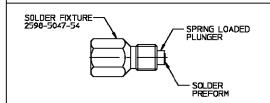
  - AT 149°C.

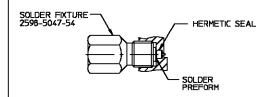
    REMOVE FROM HEAT SOURCE AND ALLOW TO FULLY COOL.

    ATTACH THE CENTER CONDUCTOR OF THE GLASS SEAL TO THE MICROSTRIP.

    UNSCREW SOLDER FIXTURE AND CLEAN SOLDERED AREA WITH SOLVENT. 2.7
  - 2.8





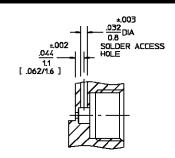




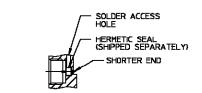
#### OPTION 2

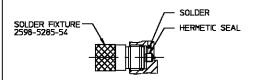
1.0 MOUNTING HOLE PREPARATION SAME AS OPTION 1 WITH THE ADDITION OF THE SOLDER ACCESS HOLE AS SHOWN.

NOTES:
1. DIMENSIONS ARE IN IN/(MM).
2. DIMENSIONS IN BRACKETS APPLY IF
STRESS RELIEF CONTACTS ARE USED.

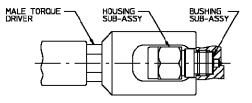


- 2.0 INSTALLATION OF HERMETIC SEAL
  2.1 CLEAN HERMETIC SEAL IN ISOPROPYL
  ALCOHOL.
  2.2 APPLY FLUX TO THE DUTER CONDUCTOR OF
  THE HERMETIC SEAL. CARE SHOULD BE
  TAKEN TO AVOID GETTING FLUX ON THE
  CENTER PIN.
  2.3 INSERT SEAL INTO THE MOUNTING HOLE
  WITH THE SHORT PIN END TOWARDS THE
  .028 ± 001 DIA HOLE, SUCH THAT THE
  PIN EXTENDS THROUGH THE PANEL AS
  SHOWN.
  2.4 SCREW THE SOLDER FIXTURE INTO THE
  MOUNTING HOLE AS SHOWN, TO HOLD
  HERMETIC SEAL IN PLACE.
  2.5 INSERT SOLDER INTO THE SOLDER ACCESS
  HOLE.
  2.6 HEAT THE PANEL TO ALLOW SOLDER TO
  FLOW. NOTE: INDALLOY #2 SOLDER FLOWS
  AT 14.9° C
  2.7 REMOVE FROM HEAT SOURCE AND ALLOW TO
  FULLY COOL.
  2.8 ATTACH THE CENTER CONDUCTOR OF THE
  GLASS SEAL TO THE MICROSTRIP.
  2.9 UNSCREW SOLDER FIXTURE AND CLEAN
  SOLDERED AREA WITH SOLVENT.





- 3.0 INSTALLATION OF THE CONNECTOR ASSY ONTO THE PANEL
  3.1 ASSEMBLE BUSHING SUB-ASSY INTO REAR OF HOUSING SUB-ASSY.
  3.2 THREAD THE CONNECTOR INTO THE PANEL MOUNTING HOLE AS SHOWN, BEING SURE THAT THE HERMETIC SEAL PIN ENTERS THE CENTER CONTACT OF THE CONNECTOR.
  3.3 TORQUE THE CONNECTOR TO 16 IN-LBS USING THE MALE TORQUE DRIVER(REF P/N 2598-5288-54).



#### \*\*\* CAUTION \*\*\*

AVOID CLEANING FLUIDS CONTAINING HALOGENATED AND AROMATIC HYDRO-CARBONS (FREON []). THESE COMPOUNDS MAY SOFTEN OR DISSOLVE THE PPO BEAD MATERIAL IN THE SUPPORT BEAD INSIDE THE BUSHING SUB-ASSEMBLY

□- TRADEMARK OF DuPONT CORP ■- TRADEMARK OF GENERAL ELECTRIC

2 of 2 Rev O